Call for Papers, Workshops, Tutorials, Special Sessions

• CASES • CODES+ISSS • EMSOFT • MEMOCODE • NOCS • Workshops • Tutorials •

About Embedded Systems Week (ESWEEK)

Embedded Systems Week (ESWEEK) is the premier event covering all aspects of hardware and software design for smart, intelligent and connected computing systems. By bringing together three leading conferences (CASES, CODES+ISSS, EMSOFT), two symposia (MEMOCODE, NOCS), and several workshops and tutorials, ESWEEK allows attendees to benefit from a wide range of topics covering the state of the art in embedded systems research and development.

One Registration, three Conferences!

Registered attendees can attend sessions in any of the ESWEEK conferences (CASES, CODES+ISSS, EMSOFT). Please note that tutorials, symposia (MEMOCODE, NOCS), and workshops may use separate registration.

Journal Track:
  Abstract Submission: March 16, 2023
  Full Paper Submission: March 23, 2023 (firm)
  Notification of Acceptance: June 30, 2023

Work-in-Progress Track:
  Paper Submission: May 22, 2023 (firm)
  Notification of Acceptance: June 19, 2023

Proposals of Workshops, Tutorials, Education Classes, and Special Sessions: March 20, 2023

All submissions are due by midnight AOE time.

ESWEEK 2023 will be an in-person event, taking place in Hamburg, Germany. We will continue to monitor specific travel advisories through official channels, which include the World Health Organization (WHO) and the local Ministry of Health. Please refer to the conference web-site and social media channels for updates.

Symposia

International Conference on Compilers, Architectures, and Synthesis for Embedded Systems

CASES is a premier forum where researchers, developers and practitioners exchange information on the latest advances in compilers and architectures for high-performance, low-power embedded systems. The conference has a long tradition of showcasing leading edge research in embedded processor, memory, interconnect, storage architectures and related compiler techniques targeting performance, power, predictability, security, reliability issues for both traditional and emerging application domains. In addition, we invite innovative papers that address design, synthesis, and optimization challenges in heterogeneous and accelerator-rich architectures.

International Conference on Hardware/Software Codesign and System Synthesis

The International Conference on Hardware/Software Co-design and System Synthesis is the premier event in system-level design, modeling, analysis, and implementation of modern embedded and cyber-physical systems, from system-level specification and optimization down to system synthesis of multi-processor hardware/software implementations. The conference is a forum bringing together academic research and industrial practice for all aspects related to system-level and hardware/software co-design.

Tutorials

Workshops

International Conference on Embedded Software

The ACM SIGBED International Conference on Embedded Software (EMSOFT) brings together researchers and developers from academia, industry, and government to advance the science, engineering, and technology of embedded software development. Since 2001, EMSOFT has been the premier venue for cutting-edge research in the design and analysis of software that interacts with physical processes, with a long-standing tradition for results on cyber-physical systems, which compose computation, networking, and physical dynamics.

Keynotes

International Symposium on Formal Methods and Models for System Design

MEMOCODE focuses on formal methods and models for developing computer systems and their components. MEMOCODE's objective is to emphasize the importance of models and methodologies in correct system design and development.

International Symposium on Networks-on-Chip

NOCS is the premier event dedicated to interdisciplinary research on on-chip, package-scale, chip-to-chip, and datacenter rack-scale communication technology, architecture, design methods, applications, and systems.

Journal-integrated Publication Model: All full papers accepted for the three conferences will be published in the **ACM Transactions on Embedded Computing Systems (TECS)**

Paper Process

ESWEEK 2023 continues a dual publication model comprising the Journal track and the Work-in-Progress (WiP) track. Journal track papers, which are full-length papers describing mature work, will be published in the ACM Transactions on Embedded Computing Systems (TECS). The WiP track papers, which are short (2-page) papers representing not-yet-mature but promising research, will be published in the ESWEEK proceedings and will be listed as regular publications within the IEEE and/or ACM digital libraries. Authors of WiP papers have the opportunity to publish the extended form of their work in any conference or journal they prefer. Journal and WiP papers are mutually exclusive, i.e., a work can only be in submission in one of the two tracks. For more information on the publishing process, refer to
http://www.esweek.org/author-information.

Workshops, Tutorials, Special Sessions

Call for Workshop Proposals

ESWEEK 2023 will host several workshops on September 21/22 and is soliciting proposals for new and recurring workshops. Workshops can be half-day to two-day long. We invite you to submit workshop proposals on any topic related to the broad set of research and education.

Call for Tutorial Proposals

ESWEEK 2023 is looking for high-quality tutorials that will take place on Sunday, September 17, 2023. Tutorials on all topics related to embedded system design, analysis, and development are welcome. Tutorials can be either half/full-day, lecture style or hands-on.

Call for Education Proposals

ESWEEK 2023 will host several education lectures *virtually* on September 14 and 15, and is soliciting proposals for such lectures. The theme of this year's Education lectures is "*Domain-Specific Hardware and Software*". We invite you to submit education proposals on a topic related to this theme.

Call for Special Session Proposals

We invite you to submit special session proposals on any topic relevant to the broad areas of interest of ESWEEK. The special session should cover a topic that is contemporary, hot, and complementary to the regular sessions. The special session should be able to generate enthusiasm among the ESWEEK participants.

Special Day Topic: Global Semiconductor Renaissance

The semiconductor industry and research are garnering tremendous interest worldwide. Embedded computing plays a key role in modern digital systems and that role will grow with the semiconductor renaissance. ESWEEK 2023 welcomes proposals on special sessions, panels, workshops, tutorials, and education classes that explore the embedded computing's role in the future of semiconductors and electronics.

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